



FUKUCOM COMPANY LTD.

福 靈 有 限 公 司

FLAT P, 3/F., EVEREST INDUSTRIAL CENTRE, 396 KWUN TONG ROAD,
KWUN TONG, KOWLOON, HONG KONG.

TEL: 852-2790 0314 FAX: 852-2790 0206



S1A THRU S1M

FEATURES

- Plastic package has Underwriters Laboratory Flammability Classification 94V-0
- For surface mounted applications
- Low profile package
- Built-in strain relief, ideal for automated placement
- Glass Passivated chip junction
- High temperature soldering:
250°C/10 seconds at terminals.

MECHANICAL DATA

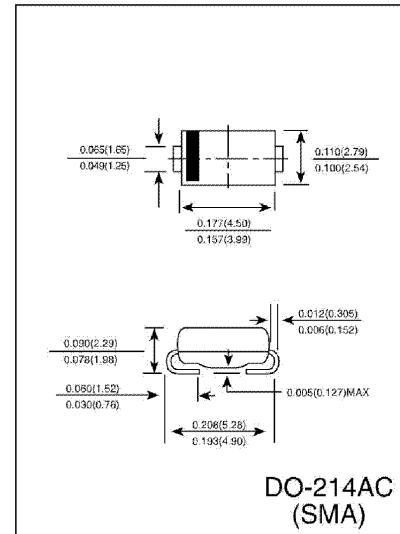
- Case: JEDEC DO-214AC molded plastic over glass passivated chip
- Terminals: Solder plated, solderable per MIL - STD - 750, Method 2026
- Polarity: Color band denotes cathode end
- Weight: 0.002 ounce, 0.064 gram

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

- Ratings at 25°C ambient temperature unless otherwise specified

Maximum Ratings & Thermal Characteristics

Parameter	Symbol	S1A	S1B	S1D	S1G	S1J	S1K	S1M	Unit
Device marking code		SA	SB	SD	SG	SJ	SK	SM	
Maximum recurrent peak reverse voltage	V _{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS voltage	V _{RMS}	35	70	140	280	420	560	700	V
Maximum DC blocking voltage	V _{DC}	50	100	200	400	600	800	1000	V
Maximum average forward rectified current (see fig.1)	I _{F(AV)}				1.0				A
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method) T _L =110°C	I _{FSM}			40		30			A
Typical thermal resistance (NOTE 1)	R _{θJA} R _{θJL}			75		85			°C/W
				27		30			
Operating junction and storage temperature range	T _J , T _{TSG}			−55 to +150					°C



DO-214AC
(SMA)

Electrical Characteristics Ratings at 25°C ambient temperature unless otherwise specified.

Parameter	Symbol	S1A	S1B	S1D	S1G	S1J	S1K	S1M	Unit
Maximum instantaneous forward voltage at 1.0A	V _F			1.10					V
Maximum DC reverse current at Rated DC blocking voltage	I _R T _A =25°C T _A =125°C			1.0		5.0			
				50					μA
Typical reverse recovery time at I _F = 0.5A, I _R = 1.0A, I _{rr} = 0.25A	t _{rr}			1.8					μs
Typical junction capacitance at 4.0V, 1MHz	C _J			12					pF

Note: (1) Thermal resistance from junction to ambient and from junction to lead mounted on P.C.B. with 0.2 x 0.2" (5.0 x 5.0mm) copper pad areas



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RATINGS AND CHARACTERISTIC CURVES S1A THRU S1M

Fig. 1 – Forward Current Derating Curve

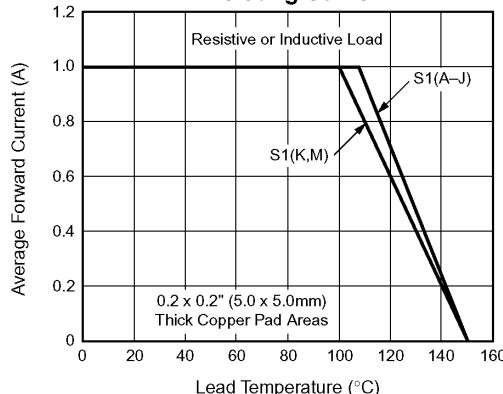


Fig. 2 – Maximum Non-Repetitive Peak Forward Surge Current

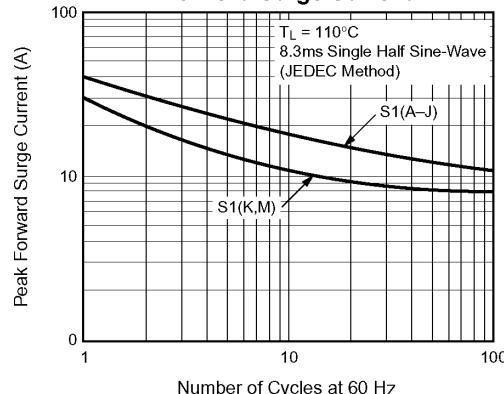


Fig. 3 – Typical Instantaneous Forward Characteristics

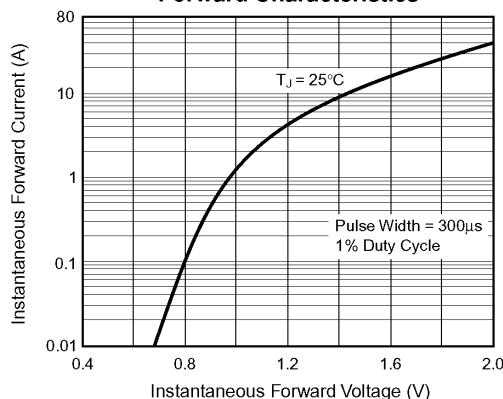


Fig. 4 – Typical Reverse Leakage Characteristics

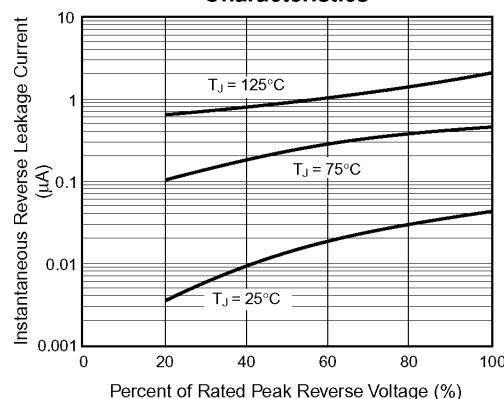


Fig. 5 – Typical Junction Capacitance

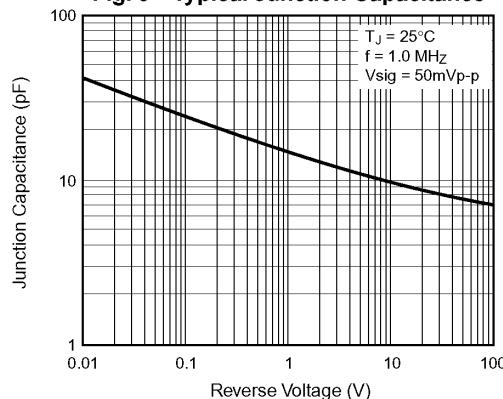


Fig. 6 – Transient Thermal Impedance

